



500.38090X00

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE
Applicant: T. WATANABE ET AL.
Serial No.: 09/462,796
Filed: January 13, 2000
For: SEMICONDUCTOR DEVICE, MOUNTING STRUCTURE
THEREOF AND METHOD OF FABRICATION THEREOF
Group: 2811
Examiner: N. Parekh

#14/E
5/4/02
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AMENDMENT

Assistant Commissioner
for Patents
Washington, D.C. 20231

April 29, 2002

Sir:

In response to the Office Action dated January 28, 2002,
please amend the above-identified application as follows:

In the Claims:

Please amend claims 2-5 and 9-19 as follows:

2. (Amended) A semiconductor device having a plurality of
pyramidal bump electrodes with a sharp tip, formed of
conductive materials filling up etched pyramidal holes on a
base material having a crystal orientation plane, respectively
bonded through an anisotropic conduction film onto pad
electrodes arranged on a semiconductor chip.